

2SC5592

Silicon NPN epitaxial planar type

For DC-DC converter
For various driver circuits

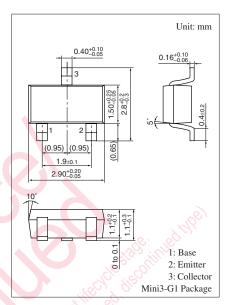
■ Features

- Low collector-emitter saturation voltage V_{CE(sat)}
- High-speed switching
- Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	15	V	
Collector-emitter voltage (Base open)	V _{CEO}	15	V	
Emitter-base voltage (Collector open)	V _{EBO}	5	V	
Collector current	I_C	2.5	A	
Peak collector current	I _{CP}	10	A	
Collector power dissipation *	P _C	600	mW	
Junction temperature	T_j	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	

Note) *: Measure on the ceramic substrate at 15 mm \times 15 mm \times 0.6 mm



Marking Symbol: 2T

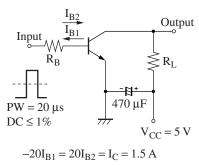
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

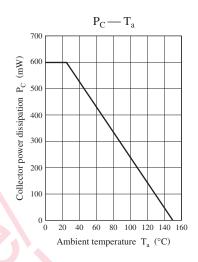
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = 10 \mu{\rm A}, I_{\rm E} = 0$	15			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = 1 \text{ mA}, I_B = 0$	15			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 10 \mu\text{A}, I_C = 0$	5			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 10 \text{ V}, I_{E} = 0$			0.1	μΑ
Forward current transfer ratio *	h _{FEI}	$V_{CE} = 2 \text{ V}, I_{C} = 100 \text{ mA}$	400		1 000	_
	h _{FE2}	$V_{CE} = 2 \text{ V}, I_{C} = 2.5 \text{ A}$	280			
Collector-emitter saturation voltage *	V _{CE(sat)}	$I_C = 1 \text{ A}, I_B = 10 \text{ mA}$		110		mV
	Co	$I_C = 2.5 \text{ A}, I_B = 50 \text{ mA}$		220	320	
Transition frequency	f_T	$V_{CB} = 10 \text{ V}, I_E = -50 \text{ mA}, f = 200 \text{ MHz}$		180		MHz
Collector output capacitance	C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		30		pF
(Common base, input open circuited)						
Turn-on time	t _{on}	Refer to the switching time measurement circuit		30		ns
Storage time	t _{stg}			100		ns
Fall time	t _f			10		ns

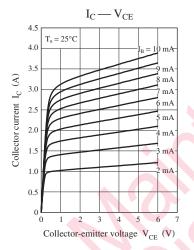
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

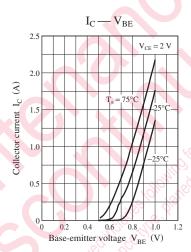
2. *: Pulse measurement (≤ 1 ms)

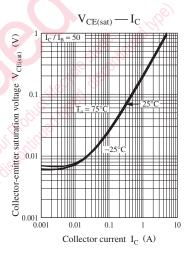
Switching time measurement circuit

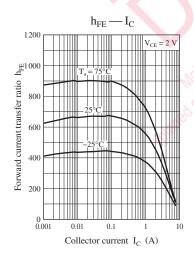


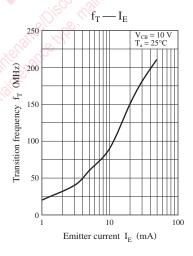


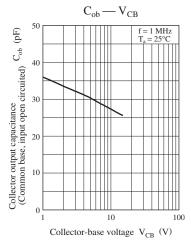












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